WaferBOND® CR-200

Temporary Bonding Material

WaferBOND® CR-200 temporary bonding material enables back-end-of-line processing of ultrathin wafers with standard semiconductor equipment.

PROCESSING

Best known methods

	20-μm process
Coat	
Spin speed	1200 rpm
Acceleration	3000 rpm/s
Time	30 s
Bake	
Bake 1	120°C, 3 min
Bake 2	180°C, 4 min
Bond	
Temperature	180°C
Force	3500 N
Time	2 min
Vacuum	≤ 5 mbar

Storage Conditions

Store at room temperature (16° to 26°C)

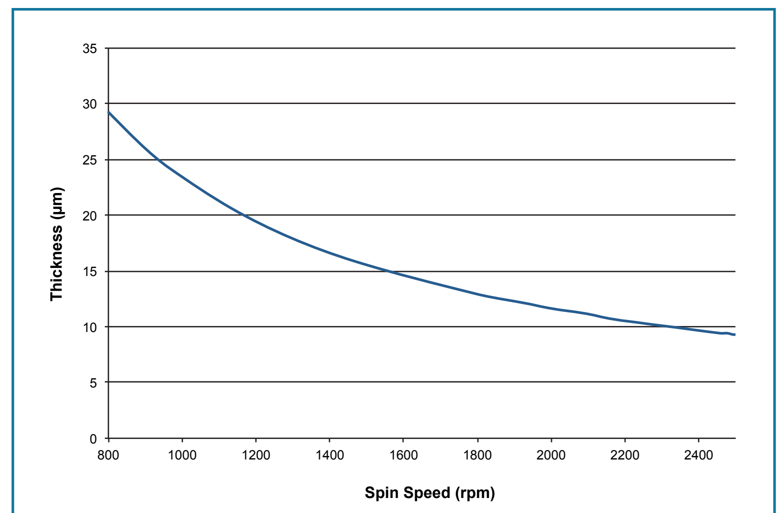
Debonding Process (Two-Bath Process)

- Bath 1: Submerge in WaferBOND® Remover material at 110° to 130°C for 1 to 4 hours, or until debonded.
- Bath 2: Clean up with WaferBOND® Remover material at 70° to 110°C for 15 minutes to 1 hour. Mild circulation is recommended.
- Rinse: Isopropanol (IPA)
- Dry

BENEFITS

- Process ultrathin wafers using standard lithographic, passivation, and metallization techniques and tooling
- Create interconnects before or after thinning
- Preserve delicate structures or III-V devices

Spin Speed Curve



Resistance to Process Chemicals

Chemistry	Bath Temp.	Time
Acetone	25°C	25 min
NMP	85°C	60 min
6N HCl	60°C	30 min
15% H_2O_2	60°C	40 min
30% NH_4OH	25°C	30 min
10% KI in H_2O	25°C	20 min
Ethanol	25°C	5 min
Methanol	25°C	5 min
Isopropanol	25°C	5 min
Cyclohexanone	25°C	5 min
Ethyl Lactate	25°C	5 min
PGMEA	25°C	5 min
PGME	25°C	5 min
30% HCl	25°C	90 min
70% HNO_3	25°C	60 min
Note: An HMDS pretreatment is recommended for the following exposure recipes:		
0.26N TMAH	60°C	30 min
30% KOH	85°C	60 min

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